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INTERIM ENGINEERING REPORT

NO.1

INTEGRATED CIRCUIT STUDY

64-5

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This report covers the period 1 June thru 31 August 1963

UNIVAC

DIVISION OF SPERRY RAND CORPORATION UNIVAC PARK, ST. PAUL 16, MINNESOTA

NAVY DEPARTMENT NObsr 89341

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BUREAU OF SHIPS

September 1963

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ABSTRACT

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This report describes the progress achieved in the integrated circuit study program for the CP-667 Computer.

Significant accomplishments were recorded in the following areas: selection of a circuit type and performance testing of existing available integrated circuits. .

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PART I

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Section 1

PURPOSE

This study is intended to compare monolithic integrated circuits, capable of performing in the CP-667 Computer, with the present hybrid (multiple chip) micro circuits per MIL-M-23700/1 thru 5.

Electrical performance, functional stability and reliability are to be evaluated.

Section 2

GENERAL FACTUAL DATA

IDENTIFICATION OF PERSONNEL

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PERSONNEL	JUNE (160 Hrs.)	JULY (200 Hrs.)	AUGUST (160 Hrs.)
Granberg	0	5	15
Janisch	· 0	0	38
Magnuson	0	Ō	1
Schipp	0	Ō	1 1
Sundem	Ō	6	24
Wheeler	Ì	Ō	
Wozniczka	0	24	108

The following list summarizes the personnel actively working on the project for each month during the period of this report:

Section 3

DETAILED FACTUAL DATA

SELECTION OF CIRCUITS

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The logic circuitry of the CP-667 is made up of nine printed circuit card types described in Table I. The circuits on these cards are developed by interconnecting the hybrid (multiple chip) circuits of MIL-M-23700/1,2,3,4,5.

Integration of the hybrid circuits suggests the combination of the dicde gate and transistor gate in one package so as to provide for connection of the substrate to the most negative potential. A minimum number of integrated circuit types are desirable to keep the tooling and testing practical. The complexity of the circuitry in any one package is limited by the number of external connections. Table I provides a breakdown of three likely circuit groups employing ten external connections. The number of circuit packages required to duplicate a given card function is compared with the presently used hybrid packages. The use of external collector resistors, and performing the "or" function at the collectors were factors in this summary.

The optimum circuit group in terms of simplicity and versatility is the 3/3 and 2/4 input combination. This is particularly desirable in view of one vendor's suggestion that the basic chip could be made with 4 input diodes on each circuit enabling either package to be made from the same chip by merely changing the final connections to the terminals.

The specification for the procurement of a 3/3 integrated circuit is attached. Subminiature resistor packages are being investigated for use as collector resistors for these circuits. This provides an option of performing the "or" function at the collector and minimizes heat dissipation within the integrated circuit.

A complementary transistor logic gate utilizing a PNP/NPN combination on one integrated chip has recently been suggested as a possible substitute for the diode gates of MIL-M-23700/1 thru 4. This system could ideally permit logic (and/or functions) to be performed without inversion at the base of the inverter circuit (MIL-M-23700/5). This phase of the program requires more circuit research before specification and procurement can be initiated.

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FRELIMINARY STUDIES

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Westinghouse type 2201 integrated Diode Transistor Logic (DTL) circuits were tested in the circuit of Figure 1. The series string was driven by and loaded with a CP-667 hybrid circuit. Figure 2a shows waveforms at each node in this configuration when no collector resistors, R_c , were used with the 2201 circuits. Figure 2b illustrates the waveforms at the same nodes with 400 ohm collector resistors. Propagation times (measured from 10% of final voltage level of the input to 10% of the final voltage level of the output) through each of the stages are summarized below:

NODE	R _e =	= 00	$R_c = 40$	OO OHM
MCD2	TURN ON	TURN OFF	TURN ON	TURN OFF
II	17 ns	17 ns	12 ns	8 ns
III	46	16	16	26 ·
IV	42	20	16	18
V	40	12	15	20

It should be noted that this represents a best case condition since the fan-out was unity and nominal conditions existed. The waveshape of the present hybrid CP-667 circuit (Node I) has a much faster rise and fall time than that of the integrated 2201 circuits. This can be attributed to the absence of parasitics in the hybrid circuits and the higher power level of the circuit.

An existing UNIVAC integrated logic circuit was wired in a series string driven by and driving a CP-667 hybrid circuit as shown in Figure 3. Figure 4 shows the waveforms at each node in the configuration. Propagation times (10% to 10% levels) for each node are shown below:

NODE	TURN ON	TURN OFF
п	12 ns 33	30 ns 30

Again note that the waveshape of the CP-667 hybrid circuits was superior to that of the tested parts. This sharp rise time accounts for the fast turn on of Node II. This circuitry is slower than the 2201 circuitry when operated with a collector resistor.

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Section 4

CONCLUSIONS

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The preliminary studies of two types of integrated circuits indicate that speeds in the range required for the CP-667 are possible from integrated circuits when operated at the same power level. The "or" function must be performed at the collector rather than the bases in order to minimize the base overdrive and subsequent increase in storage time. \$

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PART II

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PROGRAM FOR NEXT QUARTER

- 1. Procure hybrid circuits for comparison with integrated devices.
- 2. Arrange to procure from two manufacturers of integrated circuit samples of the 3/3 DTL circuit described in the attached specification.
- 3. Perform exploratory testing of the Complementary Transistor Logic Gate and prepare procurement specification for this circuit.
- 4. Procure samples of subminiature resistor package for use as collector resistors.
- 5. Establish an environmental test program designed to most efficiently determine modes of failure and degradation of characteristics.

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PART III

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SUPPLEMENTARY DATA

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. TLUDALD	PRESENT	CP-667	(птинти)	2	4	4	4	ŝ	e	9	రు	4	TABLE I
	CARD FUNCTION			22/22/22/22	333/334	3/4/3/4	2222/2222/2222	2/2/2/2/2/1	8/8	22222/22222	FF - 22228 120/22228 120	FF - 33S 3C/33S 3C	
	667 MACHINE			143	127	138	155	349	111 ¹	4	546	4671	72 of those for memory Input reduced by one At reduced spood
	CARD ASSEMBLY		· ·	4224000	4224010	4224020	4224030	1224040	4224050	4224060	4224070	4224080	1 72 of those 2 Input reduce 3 At reduced

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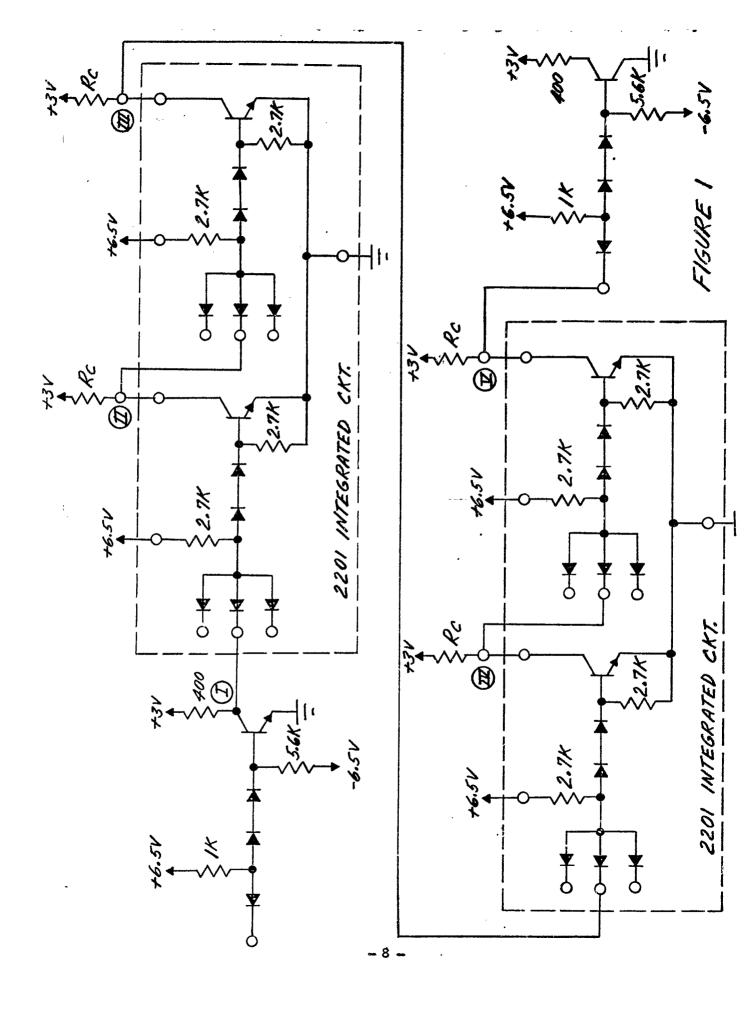
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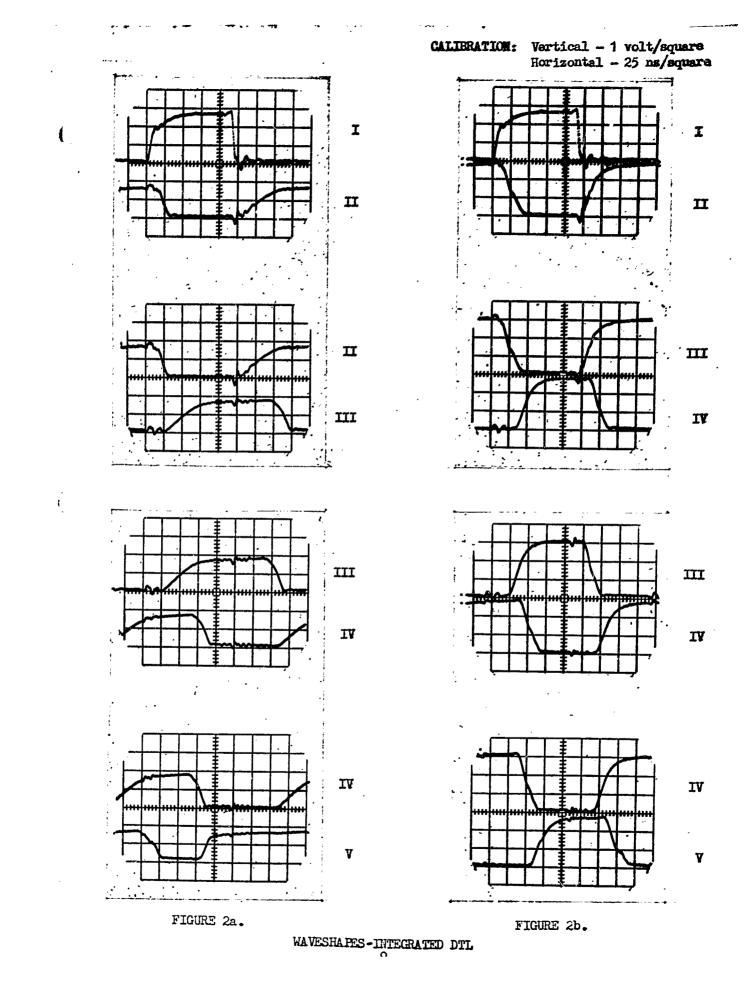
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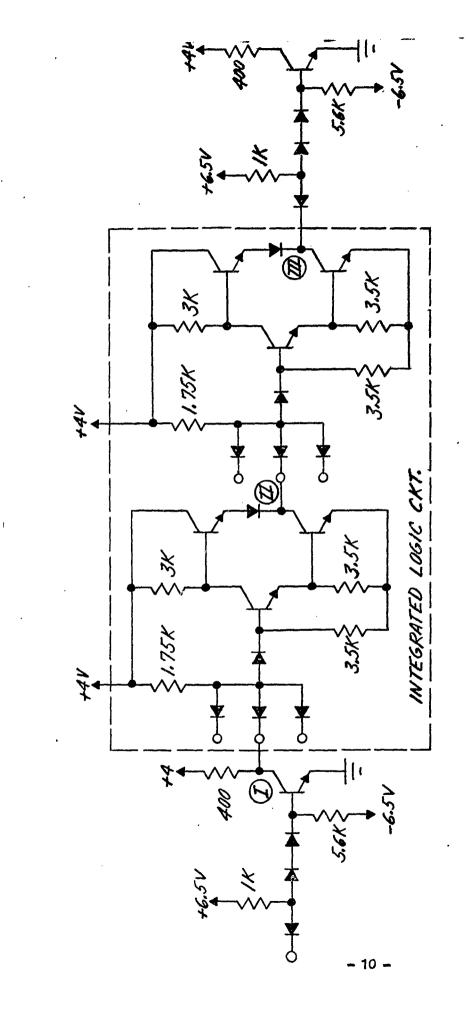
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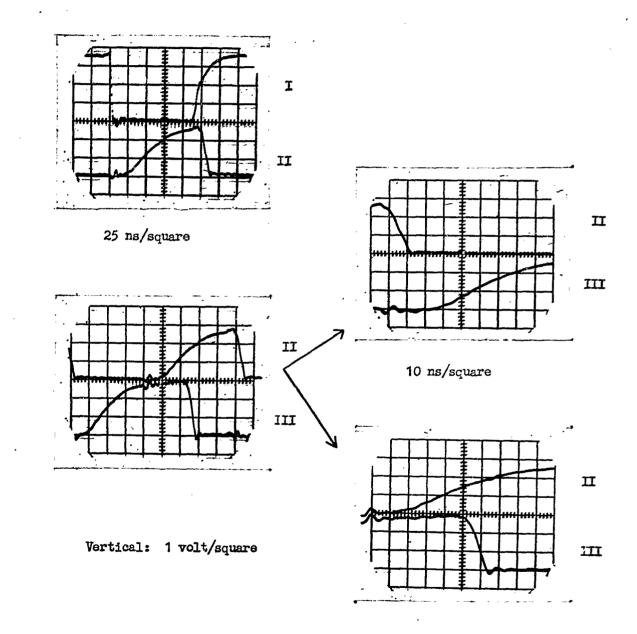






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FIGURE 3



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FIGURE 4. WAVESHAPES - INTEGRATED LOGIC CIRCUIT

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A. New Circuits	PI																		
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4. Reports	R	1																	

LEGEND

- PI Preliminary Investigation
- VL Vendor Liaison
- SP Specification Preparation PP Procurement

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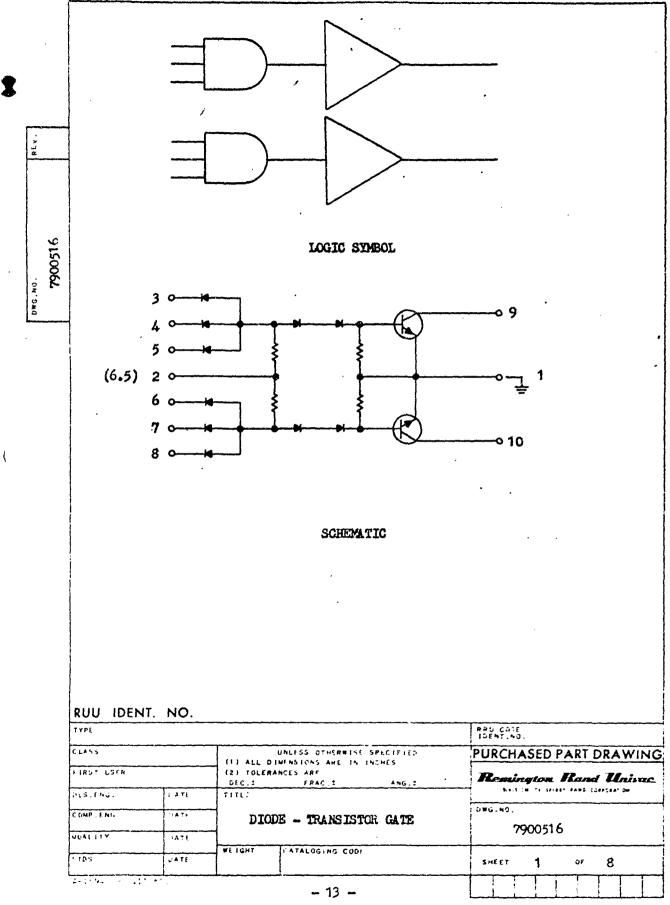
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- TC Test Circuits
- FT Functional Test

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- FI Functional lest
 ET Environmental Test
 FA Failure Analysis
 R Reports
 Work Schedule Complete
- = Work Schedule Proposed



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	I.	APPLICABLE	SPECIFICATIONS					
	l		3700 (Navy)					
	II.	CONSTRUCTIO	IN AND DIMENSIONS	\$	(As shown in	ı Figu	re 3)	
	III.		CHARACTERISTICS	ۇ	(As shown in	ı Table	ə I)	
	·	<u>Maximum Rat</u>	T	<u> </u>	r			1
	P) (Iotal)	Device Operat Above 25°C	ing	R1 or R2 Dissipation		sistor rating	Temperature Range
		200 m.	1.3 ms/°C		100 mm	0.6	67 <u>≖</u> µ/°C	-65 to +175°C
	IV.	QUALITY ASS	URANCE HOVISION	CRIPTION			CATE	COMP ENG ASSURANCE STO
				RE	VISIONS			
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		TOEXIS		I2-3 thru 8 I1-9 I10 I2-1	13 thru 8-2 1-2	रू । न	V9-1 (Sat) V10-1 (Sat)
	TABLE I.	SHECIFIC COLDITIONS		V_{2-3} thru $B = 6.5$ Vdc V_{1-5} = 4.5 Vdc V_{1-10} = 4.5 Vdc V_{2-1} = 6.5 Vdc	$\mathbf{V}_{1}^{2} \text{ thru } \mathbf{B}_{-2} = 4.5 \text{ Vac}$ $\mathbf{V}_{1-2}^{2} = 4.5 \text{ Vac}$	See Figure 4 Connect 2 to C Connect 1 to D Alternately connect 3, 4, 5, 6, 7, 8 to B	See Figure 5 Connect 1 to C Connect 2 to A Connect 3 thru 8 to +2.4 Wic Alternately connect 9 and 10 to B
		LSEI	Visual & Mechanical	Forward Current	Raverse Current	Diode Effective Speed	Eaturation Voltago (Requires effective hrg Min = 40)
·	3-14	UTH	-	ર્સ	DESCRIPTION	4	DATE COMP ENG JUAL
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(TABLE I. (Cont.)		SHULTURE OLITOTA	See Figure 6 Connect 1 to 0 2 to 4A 9 to 4B Alternately connect 3, 4,		Connset 1 to C 2 to A 10 to B Alternstely contact 6, 7, to D	rre 7 1 to C 2 to +A).o.	CRD	6, 7, 8 & 10	3,4,5 & 9	Ð	Except R _c = 400 0hms
		CT.NT	Intae	See Figure 6 Connect 1 to 0 2 to 4A 9 to 4B Alternately conn	to D	Connect 1 to C 2 to A 10 to B Alternstely con to D	See Figure 7 Connect 1 to C Connect 2 to $+1$ $R_{c} = 100 \dots$	Alternately Supply Input to	m 410	836	Ав Ароче	Except]
				o. Noise Rejection			/. Turn-On This	·	,		. Turn-Off This	
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